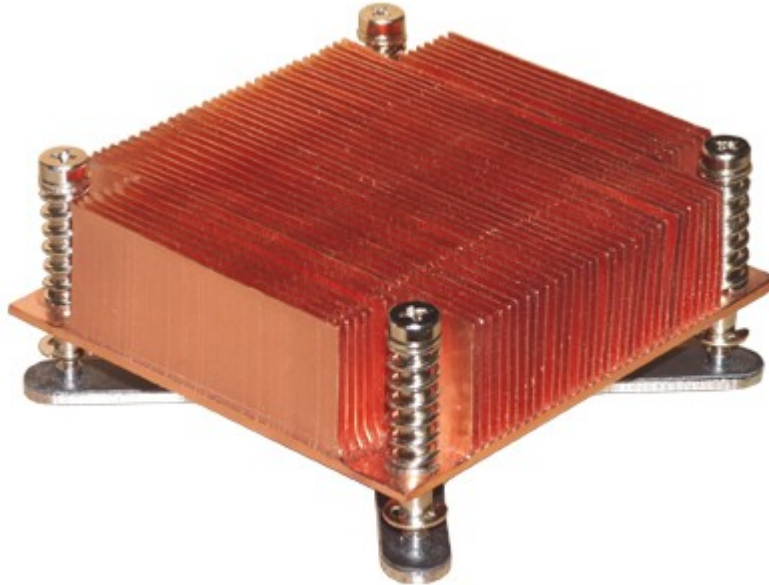


SP588-1U



SP588-1U is a thermally advanced passive heat-sink solution for Intel LGA 775 processors in 1U server chassis. The heatsink is made of pure copper with skived fins technology ensuring rapid heat transfer and efficient dissipation. Pre-applied spring-screws and mainboard back-plate guarantee safe and secure installation.

Main Features:

- * Pure copper heat-sink
- * Low profile - 1U (rack-mount application only)
- * Passive heat-sink 0dBA
- * Most effective with indirect air-ducting

Product Specification

Socket 775 Cooling kit

Dimensions	Heat sink : 87×83×27 mm (l × w × h)
Noise level	0 dBA
Air flow	0 CFM (fanless solution)
Features	All Copper Heatsink, 1U Rackmount
Connector	N.A.
Application	Intel : Celeron D ~ 2.93 GHz (340J) Intel : Core 2 Duo ~ 3 GHz (775 Dual-core) Intel : Core 2 Quad ~ 2.66 GHz (775 Quad-core) LGA775 ~ 3.73 GHz (Prescott) Pentium D ~ 3.4 GHz (775 Dual-Core)
Thermal resistance	5M/s Flow Speed 0.28 °C/W
Thermal type	Stars-420 white grease(Injection Tube,0.5g)